

GOLD-COATED SILVER BONDING WIRE AND MANUFACTURING METHOD
THEREOF, AND SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD
THEREOF

ABSTRACT

A gold-coated silver bonding wire includes: a core material containing silver as a main component; and a coating layer provided on a surface of the core material and
5 containing gold as a main component. The gold-coated silver bonding wire contains gold in a range of not less than 2 mass% nor more than 7 mass%, and at least one sulfur group element selected from the group consisting of sulfur, selenium, and tellurium in a range of not less than 1 mass ppm nor more than 80 mass ppm, with respect to a total content of the bonding wire.